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LithoBench: Benchmarking AI Computational Lithography for Semiconductor Manufacturing

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Introduction

Semiconductor Lithography



• Lithography prints the mask patterns to the wafer



Semiconductor Lithography



Fail to get target patterns due to distortion → Fix it by distoring the mask!



Mask Optimization



• OPC vs. ILT

Optical Proxim	mity Correction	Inverse Lithography Technology						
45 nm	28 nm	14 nm	7 nm					
node	node	node	node					
without	normal	normal	ideal					
OPC	OPC	ILT	ILT					
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Mask Optimization



• Inverse Lithography Technology (ILT) \rightarrow Iterative Optimization



ILT Refinement $\boldsymbol{R}(\boldsymbol{M}_{init}, \boldsymbol{T})$

Optimized Mask M^*

Mask Optimization



• DNN-based ILT \rightarrow End-to-end, Faster



LithoBench Tasks



- **Lithography simulation**: mask → printed image (DNN Litho)
- **Mask optimization**: target image → optimized mask (DNN ILT)



Dataset

Layered Circuit Layout

A circuit layout consists of multiple layers
 → Each one can be modeled by an image



LithoBench Subsets



- **MetalSet**: train DNN-based models for metal layers, compatible with the famous ICCAD-13 benchmark¹
- **ViaSet**: train DNN-based models for via layers, compatible with the setting of related works
- **StdMetal**: test the generalization ability of the model trained on MetalSet, which is a challenging task
- **StdContact**: test the generalization ability of the model trained on ViaSet, which is very challenging

¹Shayak Banerjee, Zhuo Li, and Sani R Nassif (2013). "ICCAD-2013 CAD contest in mask optimization and benchmark suite". In: *IEEE/ACM International Conference on Computer-Aided Design (ICCAD)*, pp. 271–274. 12/25

Data Collection



- Data collection
 - **MetalSet**: randomly generation following the design rules of ICCAD-13 benchmark \rightarrow 16,472 tiles
 - Size: 2048 × 2048
 - Much more than ICCAD-13 (10 tiles)
 - ViaSet: cropped from the layouts gcd and aes from OpenROAD, the IC design tool → 116,415 tiles
 - **StdMetal**: cropped from the metal layer of the Nangate 45nm standard cells → 271 tiles
 - **StdContact**: cropped from the contact layer of the Nangate 45nm standard cells → 328 tiles

Task		Lithograp	hy Simulati	on	Mask Optimization					
Subsets	MetalSet	ViaSet	StdMetal	StdContact	MetalSet	ViaSet	StdMetal	StdContact		
Training Tiles	14,824	104,733	0	163	14,824	104,733	0	163		
Testing Tiles	1,648	11,642	271	165	10	10	271	165		



• Examples: (a) MetalSet; (b) ViaSet; (c) StdMetal; (e) StdContact.



Data Preparation



Lithography Simulation: Hopkins' Model
 → Different *H* for different process conditions

$$\boldsymbol{I} = \boldsymbol{H}(\boldsymbol{M}) = \sum_{k=1}^{K} \mu_k |\boldsymbol{h}_k \otimes \boldsymbol{M}|^2$$
(1)

Mask Optimization: Multi-level ILT²
 → Optimize the following loss function

$$L_f(\mathbf{Z}_{nom}, \mathbf{Z}_{max}, \mathbf{Z}_{max}, \mathbf{T}) = \|\mathbf{Z}_{max} - \mathbf{T}\|_2^2 + \|\mathbf{Z}_{max} - \mathbf{Z}_{min}\|_2^2 + L_{curv}(\mathbf{Z}_{nom})$$
(2)

$$\mathbf{Z} = \boldsymbol{\sigma}_{Z} \left(\boldsymbol{H} \left(\boldsymbol{\sigma}_{M} \left(AvgPool\left(\boldsymbol{P} \right) \right) \right) \right)$$
(3)

15/25

²Shuyuan Sun et al. (2023). "Efficient ILT via Multi-level Lithography Simulation". In: *ACM/IEEE Design Automation Conference (DAC)*.





• Lithography Simulation ($\mathbf{Z}_1 = \{\mathbf{Z} = 1\}$)

$$MSE(Z, T) = \|Z - T\|_{2}^{2}$$
(4)

$$IOU(Z, T) = \frac{Z_{1} \cap T_{1}}{Z_{1} \cup T_{1}}$$
(5)

$$PA(Z, T) = \frac{Z_{1} \cap T_{1}}{T_{1}}$$
(6)





Mask Optimization (a) L2; (b) PVB; (c) EPE; (d) #Shots



Experiments

Lithography Simulation Models

- NEURAL INFORMATION PROCESSING SYSTEMS
- LithoGAN³: A conditional GAN with a FCN generator and a CNN discriminator, 256 × 256 input/output
- **DAMO**⁴: A conditional GAN with a UNet++ generator and a pix2pixHD discriminator, 1024 × 1024 input/output
- **DOINN**⁵: A novel reduced Fourier neural operator (RFNO) architecture, 1024 × 1024 input/output
- **CFNO**⁶: Combining vision transformer (ViT) and Fourier neural operator (FNO), 1024 × 1024 input/output

³Wei Ye et al. (2019). "LithoGAN: End-to-end lithography modeling with generative adversarial networks". In: *ACM/IEEE Design Automation Conference (DAC)*.

⁴Guojin Chen et al. (2020). "DAMO: Deep agile mask optimization for full chip scale". In: *IEEE/ACM International Conference on Computer-Aided Design (ICCAD)*.

⁵Haoyu Yang, Zongyi Li, et al. (2022). "Generic lithography modeling with dual-band optics-inspired neural networks". In: *ACM/IEEE Design Automation Conference (DAC)*, pp. 973–978.

⁶Haoyu Yang and Haoxing Ren (2023). "Enabling Scalable AI Computational Lithography with Physics-Inspired Models". In: *IEEE/ACM Asia and South Pacific Design Automation Conference (ASPDAC)*, pp. 715–720.

20/25

Mask Optimization Models

- **GAN-OPC**⁷: A conditional GAN with the novel ILT-guided pretraining, 256 × 256 input/output
- **Neural-ILT**⁸: A UNet generator with complexity reduction mechanism, 512 × 512 input/output
- **DAMO**: A conditional GAN with a UNet++ generator and a pix2pixHD discriminator, 1024 × 1024 input/output
- **CFNO**: Combining vision transformer (ViT) and Fourier neural operator (FNO), 1024 × 1024 input/output

⁷Haoyu Yang, Shuhe Li, et al. (2018). "GAN-OPC: Mask optimization with lithography-guided generative adversarial nets". In: *ACM/IEEE Design Automation Conference (DAC)*.

⁸Bentian Jiang et al. (2020). "Neural-ILT: Migrating ILT to neural networks for mask printability and complexity co-optimization". In: *IEEE/ACM International Conference on Computer-Aided Design (ICCAD)*.



		LithoG.	AN	DAMO				DOINN				CFNO				
Subtask	MSE_A	MSE_P	IOU	PA	MSE_A	MSE_P	IOU	PA	MSE_A	MSE_P	IOU	PA	MSE_A	MSE_P	IOU	PA
1	$9.8_{10^{-4}}$	$1.7_{\cdot 10^{-2}}$	0.38	0.43	$8.4_{.10^{-6}}$	$7.5 \cdot 10^{-4}$	0.97	0.98	$8.5 \cdot 10^{-6}$	$6.6 \cdot 10^{-4}$	0.97	0.98	$1.9_{\cdot 10^{-5}}$	$1.5 \cdot 10^{-3}$	0.94	0.97
2	$2.6 \cdot 10^{-4}$	$1.4 \cdot 10^{-3}$	0.47	0.53	$3.0_{.10^{-6}}$	$1.5 \cdot 10^{-4}$	0.94	0.96	$1.9_{10^{-6}}$	$1.0 \scriptstyle \cdot 10^{-4}$	0.96	0.98	$3.8 \cdot 10^{-6}$	$2.1{\scriptstyle \cdot 10^{-4}}$	0.92	0.96
3	$1.4 \cdot 10^{-3}$	$2.6 \cdot 10^{-2}$	0.30	0.34	$2.5 \cdot 10^{-5}$	$1.5_{10^{-3}}$	0.95	0.97	$1.8_{10^{-5}}$	$1.2 \cdot_{10^{-3}}$	0.96	0.98	2.6.10-5	$2.3 \scriptstyle \cdot 10^{-3}$	0.93	0.96
4	$2.7_{10^{-3}}$	$1.2 \scriptstyle \cdot 10^{-2}$	0.01	0.01	$4.6 \scriptstyle \cdot 10^{-5}$	$1.6 \cdot 10^{-3}$	0.87	0.93	$2.4{\scriptstyle \cdot 10^{-5}}$	$1.3_{\cdot 10^{-3}}$	0.90	0.94	$2.1 \cdot 10^{-5}$	$2.2{\scriptstyle \cdot 10^{-3}}$	0.83	0.90
Average	$1.3{\scriptstyle \cdot 10^{-3}}$	$1.4{\scriptstyle \cdot 10^{-2}}$	0.29	0.33	$2.1{\scriptstyle \cdot 10^{-5}}$	$1.0{\scriptstyle \cdot 10^{-3}}$	0.93	0.96	$1.3_{\cdot 10^{-5}}$	$8.2 \scriptstyle \cdot 10^{-4}$	0.95	0.97	$1.7_{\cdot 10^{-5}}$	$1.5 \cdot 10^{-3}$	0.91	0.95
Runtime	0.013 s / image				0.030 s / image			0.017 s / image				0.035 s / image				

• Examples: (a)Label; (b)LithoGAN; (c)DAMO; (d)DOINN; (e)CFNO



Lithography Simulation Results







	GAN-OPC				Neural-ILT					DAM	OILT		CFNO			
Subtask	L_2	PVB	EPE	Shots	L_2	PVB	EPE	Shots	L ₂	PVB	EPE	Shots	L_2	PVB	EPE	Shots
1	43414	41290	8.7	574	36670	42666	7.3	476	32579	41173	5.4	523	47814	46131	12.5	302
2	14767	6686	8.3	166	12723	8537	6.2	263	5081	9962	0.0	176	8949	9890	0.1	184
3	25929	23715	4.6	457	20045	23548	2.4	373	16120	23796	0.2	418	26809	26814	4.2	232
4	81378	4931	73.2	276	25422	41537	3.2	265	50445	35673	26.7	458	70740	17950	55.1	396
Average	41372	19156	23.7	368	23715	29072	4.8	344	26056	27651	8.0	394	38578	25196	18.0	279
Runtime	0.010 s / image				0.025 s / image			0.028 s / image				0.040 s / image				

• Examples: (a)Label; (b)GAN-OPC; (c)NeuralILT; (d)DAMO; (e)CFNO



Mask Optimization Results





THANK YOU!